

Product data sheet

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Features

- Small plastic package suitable
- for surface mounted design
- High reliability with high surge current handling capability

Applications

• High speed switching

PINNING PIN DESCRIPTION 1 Cathode 2 Anode 1 2 SOD-323

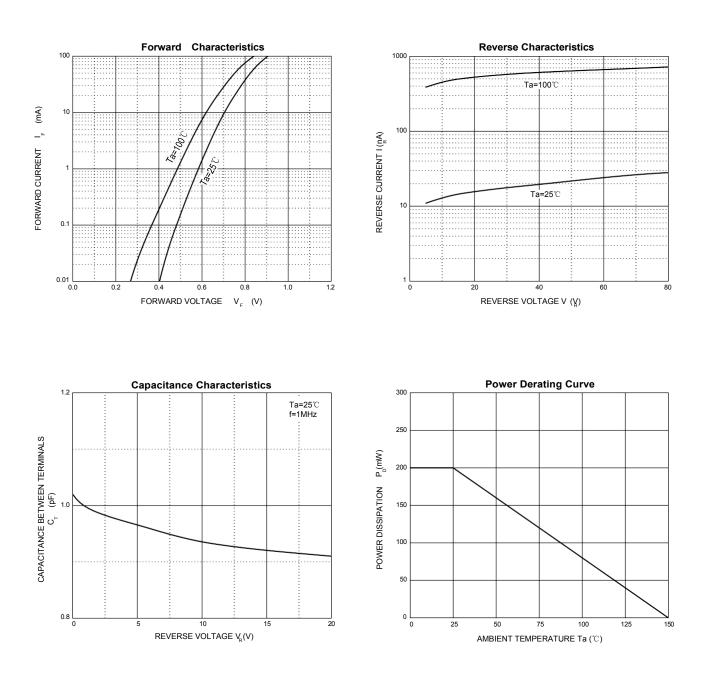
Absolute Maximum Ratings (T_a = 25 °C)

Parameter	Symbol	Value	Unit
Peak Reverse Voltage	V _{RM}	90	V
Reverse Voltage	V _R	80	V
Average Rectified Forward Current	I _{F(AV)}	100	mA
Peak Forward Current	I _{FM}	225	mA
Surge Forward Current (1 s)	I _{FSM}	500	mA
Junction Temperature	Tj	150	°C
Storage Temperature Range	T _{stg}	- 55 to + 150	°C

Electrical Characteristics (T_a = 25 °C)

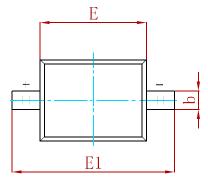
Parameter	Symbol	Max.	Unit
Forward Voltage at I _F = 100 mA	VF	1.2	V
Reverse Current at V _R = 80 V	I _R	0.1	μA
Capacitance between Terminals at V_R = 0.5 V, f = 1 MHz	Ст	3	pF
Reverse Recovery Time at V _R = 6 V, I _F = 10 mA, R _L = 100 Ω	t _{rr}	4	ns

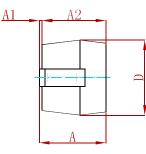


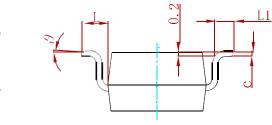




PACKAGE MECHANICAL DATA

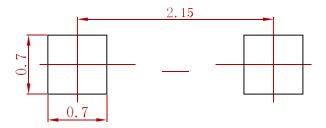






Symbol	Dimensions In Millimeters		Dimensions In Inches	
Symbol	Min.	Max.	Min.	Max.
A		1.000		0.039
A 1	0.000	0.100	0.000	0.004
A2	0.800	0.900	0.031	0.035
b	0.250	0.350	0.010	0.014
с	0.080	0.150	0.003	0.006
D	1.200	1.400	0.047	0.055
E	1.600	1.800	0.063	0.071
E1	2.550	2.750	0.100	0.108
L	0.475 REF.		0.019 REF.	
L1	0.250	0.400	0.010	0.016
θ	0°	8°	0°	8°

Suggested Pad Layout



Note:

1.Controlling dimension:in millimeters.

2.General tolerance:± 0.05mm.

3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
1SS355-MS	SOD-323	3000



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